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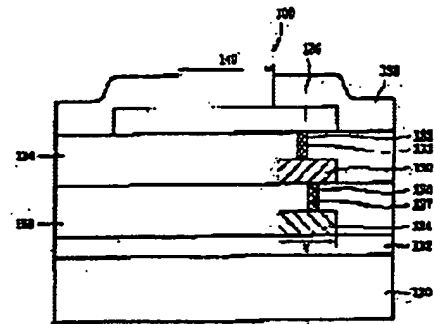
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(54) SEMICONDUCTOR ELEMENT WITH MULTILAYERED PAD, AND MANUFACTURE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor element provided with a multilayered pad, with which the generation of cracks can be minimized by optimizing the structure of a bonding pad, and to provide a manufacturing method of the semiconductor element.

SOLUTION: A first conductive pad 124, which extends long along one open face of the case part of a pad window region 140, is formed on the semiconductor substrate 120 provided with a first interlayer insulating film 122. A second interlayer insulating film 128, having a first via hole 126 used to expose the surface of the first conductive pad 124, is formed on the first interlayer insulating film 122, and a first conductive plug 127 is formed in the first via hole 126. A second conductive pad 130, to be connected to the first conductive plug 127, is formed on the second interlayer insulating film 128. A third interlayer insulating film 134, provided with a second via hole 132 used to expose the surface of the second conductive pad 130, is formed, and a second conductive plug 133 is formed in the via hole 132. A third conductive pad 136 is formed on the third interlayer insulating film 134, in such a manner that it is connected to the second conductive plug 133.



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